



EOC-GDL-1653.7-TO

Specifications 1653.7 nm, 3mW DFB TO-Can, Ball Lens

A. PRODUCT DESCRIPTION

The EOC-GDL-1653.7-TO is an InGaAsP based and cooled distributed feedback laser in a T0-60 package, with a collimated ball lens, optimized for OTDR and photonic sensing applications.

B. FEATURES

- Optical output power min. 3mW
- Lasing wavelength of 1653.7nm
- Typical SMSR >35dB

C. APPLICATIONS

- Test & Measurement (OTDR)
- Photonic Sensing (gas)
- Biomedical Sensing

D. ABSOLUTE MAXIMUM RATINGS

Operation beyond the absolute maximum ratings can cause degradation in device performance leading to permanent damage to the device.

Parameter	Symbol	Test Conditions	Min	Max	Unit
Reverse voltage	V _R	CW	-	2	v
Forward Current	IF	CW	-	100	mA
Forward Voltage	VF	CW	-	2	v
Chip Submount Temperature	Tsub	CW	5	45	°C
Case Temperature	T _{case}	-	-20	65	°C
TEC Current	I _{TEC}	-	-	0.7	А
TEC Voltage	V _{TEC}	-	-	3.5	V
Storage temperature	T _{stg}	Unbiased	-40	85	°C
Electro static discharge (ESD)	V _{ESD}	Human body model		500	v
Lead Soldering Temperature	S _{Temp}	-		220	°C
Lead Soldering Time	S _{Time}	-		10	s

E. ELECTRO-OPTICAL CHARACTERISTICS

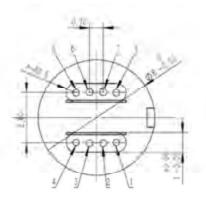
(at Tsub of 25°C and CW, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Optical output power	Po	-	3	-	-	mW
Threshold current	I _{th}	-	-	11	26	mA
Operating current	I _{op}	P _{0min}	30	40	55	mA
Forward voltage	V _{op}	P _{0min}	-	1.6	2.0	V
Slope efficiency	η	P _{0min}	0.1	0.15	-	mW/mA
Peak wavelength	λ_p	I _{op} = 35mA	1651. 7	1653.7	1655.7	nm
Side mode suppression ratio	SMSR	I _{op} = 35mA	35	40	-	dB
Wavelength Temperature Tuning Coefficient	⊗L/⊗т	I _{op} = 35mA	-	0.1	-	nm/°C
Wavelength Current Tuning Coefficient	⊗L/⊗ı	I _{op} = 35mA to 55mA	-	0.03	-	nm/mA
Monitor current	Im	P _{0min}	0.02	-	-	mA
Thermistor Resistance	RT	-	-	10	-	kΩ
Thermistor B-value	В	-	-	3930	-	к
Beam divergence (FWHM) perpendicular	FFV	P _{0min}	-	-	2	ō
Beam divergence (FWHM) parallel	FFH	P _{0min}	-	-	2	ō

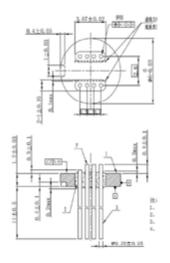
Note: T_{sub} is measured by a thermistor soldered on the submount where the laser diode chip is soldered on to.

F. PHYSICAL DIMENSIONS AND MECHANICAL SPECIFICATION Bottom view pin out Bottom View

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Pin Assignment	Type R	Type S
1	TEC-	TEC-
2	TM+	TM+
3	TM-	LD+
4	PD-	PD-
5	PD+	PD+
6	LD-	LD-
7	LD+	TM-
8	TEC+	TEC+



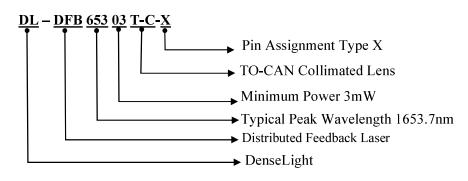
TO-60 Drawing



G. DISCLAIMER FOR CUSTOMER SPECIFIC APPLICATIONS

This product is not intended for use other than stated on the application note or as defined in the product specification. The performance of the product should always be tested in the actual application conditions. As our products are used in conditions beyond our control, we cannot assume any liability for damage caused through their use. Users of our products are solely responsible to thoroughly test and qualify their system and/or application for their intended application and have determined such at their sole discretion. We cannot assume any liability for the use of our products in conjunction with others. Customer assumes the sole risk and liability of the product performance other than specified by the product specific data sheet or application notes without our specific written consent. We reserve the right to change prices, features, functions, specification, capabilities and release schedules as per notifications to the customer.

H. PRODUCT NAMING



To order TO60 with TEC Type-R 8pins out, please order DL-DFB65303T-C-R

To order TO60 with TEC Type-S 8pins out, please order DL-DFB65303T-C-S